

Title (en)
METHOD AND DEVICE FOR ENCAPSULATING ELECTRONIC COMPONENTS WHILE EXERTING FLUID PRESSURE

Title (de)
VERFAHREN UND ANORDNUNG ZUM EINKAPSELN ELEKTRONISCHER BAUELEMENTE UNTER AUSÜBUNG EINES FLUIDDRUCKES

Title (fr)
PROCEDE ET DISPOSITIF D'ENCAPSULATION DE COMPOSANTS ELECTRONIQUES ET, SIMULTANEMENT, D'APPLICATION D'UNE PRESSION FLUIDIQUE

Publication
EP 1456878 A2 20040915 (EN)

Application
EP 02783856 A 20021205

Priority
• NL 0200797 W 20021205
• NL 1019514 A 20011207

Abstract (en)
[origin: WO03049177A2] The invention relates to a method for encapsulating electronic components, in particular semiconductors, by receiving a component for encapsulating between two mould halves displaceable relative to each other and feeding a liquid encapsulating material under overpressure by means of a transfer mechanism to at least one mould cavity arranged for this purpose, characterized in that during feeding of liquid encapsulating material to the mould cavity the part of the mould cavity not yet filled with encapsulating material is filled with a gas under overpressure. The invention also relates to a device for encapsulating electronic components.

IPC 1-7
H01L 21/56

IPC 8 full level
B29C 45/14 (2006.01); **B29C 45/17** (2006.01); **H01L 21/56** (2006.01)

CPC (source: EP KR US)
B29C 45/14655 (2013.01 - EP US); **B29C 45/1703** (2013.01 - EP US); **H01L 21/56** (2013.01 - KR); **H01L 21/565** (2013.01 - EP US); **H01L 2224/32225** (2013.01 - EP US); **H01L 2224/4824** (2013.01 - EP US); **H01L 2224/73215** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US)

Citation (search report)
See references of WO 03049177A2

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR IE IT LI LU MC NL PT SE SI SK TR

DOCDB simple family (publication)
WO 03049177 A2 20030612; **WO 03049177 A3 20031016**; AU 2002347678 A1 20030617; EP 1456878 A2 20040915; KR 20040064729 A 20040719; NL 1019514 C2 20030611; US 2005062199 A1 20050324

DOCDB simple family (application)
NL 0200797 W 20021205; AU 2002347678 A 20021205; EP 02783856 A 20021205; KR 20047008741 A 20021205; NL 1019514 A 20011207; US 49772104 A 20041116